

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^{a, e}	Q_g (Typ.)
- 20	0.073 at $V_{GS} = - 4.5$ V	- 3.4	6.9 nC
	0.125 at $V_{GS} = - 2.5$ V	- 2.6	

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Ultra-Small 1 mm x 1 mm Maximum Outline
- Ultra-Thin 0.548 mm Maximum Height
- Compliant to RoHS Directive 2002/95/EC



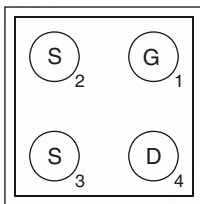
RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

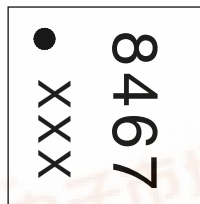
- Load Switches, Battery Switches and Charger Switches in Portable Device Applications
- DC/DC Converters

MICRO FOOT

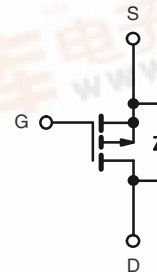
Bump Side View



Backside View



Device Marking: 8467
xxx = Date/Lot Traceability Code



P-Channel MOSFET

Ordering Information: Si8467DB-T2-E1 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	$T_A = 25^\circ\text{C}$	A
		$T_A = 70^\circ\text{C}$	
		$T_A = 25^\circ\text{C}$	
		$T_A = 70^\circ\text{C}$	
Pulsed Drain Current	I_{DM}	- 15	W
Continuous Source-Drain Diode Current	I_S	$T_C = 25^\circ\text{C}$	
		$T_A = 25^\circ\text{C}$	
Maximum Power Dissipation	P_D	$T_A = 25^\circ\text{C}$	
		$T_A = 70^\circ\text{C}$	
		$T_A = 25^\circ\text{C}$	
		$T_A = 70^\circ\text{C}$	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$
Package Reflow Conditions ^c	VPR	260	
	IR/Convection	260	

Notes:

- Surface mounted on 1" x 1" FR4 board with full copper, $t = 10$ s.
- Surface mounted on 1" x 1" FR4 board with minimum copper, $t = 10$ s.
- Refer to IPC/JEDEC (J-STD-020C), no manual or hand soldering.
- In this document, any reference to case represents the body of the MICRO FOOT device and foot is the bump.
- Based on $T_A = 25^\circ\text{C}$.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, b}	$t = 10 \text{ s}$	55	70	°C/W
Maximum Junction-to-Ambient ^{c, d}	$t = 10 \text{ s}$	125	160	

Notes:

a. Surface mounted on 1" x 1" FR4 board with full copper.

b. Maximum under steady state conditions is 100 °C/W.

c. Surface mounted on 1" x 1" FR4 board with minimum copper.

d. Maximum under steady state conditions is 190 °C/W.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 13		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			3.1		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.6		- 1.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 70 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 5 V, V _{GS} = - 4.5 V	- 10			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 1 A		0.06	0.073	Ω
		V _{GS} = - 2.5 V, I _D = - 1 A		0.102	0.125	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 10 V, I _D = - 1 A		6		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		475		pF
Output Capacitance	C _{oss}			135		
Reverse Transfer Capacitance	C _{rss}			110		
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 10 V, I _D = - 1 A		14	21	nC
		V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 1 A		6.9	11	
Gate-Source Charge	Q _{gs}			1		
Gate-Drain Charge	Q _{gd}			2.4		
Gate Resistance	R _g	V _{GS} = - 0.1 V, f = 1 MHz		6		Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 10 Ω I _D ≅ - 1 A, V _{GEN} = - 4.5 V, R _g = 1 Ω		25	50	ns
Rise Time	t _r			22	45	
Turn-Off Delay Time	t _{d(off)}			25	50	
Fall Time	t _f			10	20	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 10 Ω I _D ≅ - 1 A, V _{GEN} = - 10 V, R _g = 1 Ω		7	15	
Rise Time	t _r			10	20	
Turn-Off Delay Time	t _{d(off)}			22	45	
Fall Time	t _f			10	20	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _A = 25 °C			- 1.5	A
Pulse Diode Forward Current	I _{SM}				- 15	
Body Diode Voltage	V _{SD}	I _S = - 1 A, V _{GS} = 0 V		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 1 A, dI/dt = 100 A/μs, T _J = 25 °C		22	40	ns
Body Diode Reverse Recovery Charge	Q _{rr}			10	20	nC
Reverse Recovery Fall Time	t _a			8		ns
Reverse Recovery Rise Time	t _b			14		

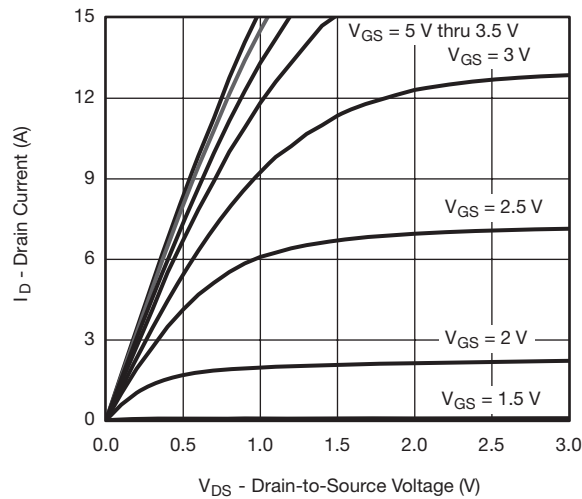
Notes:

a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

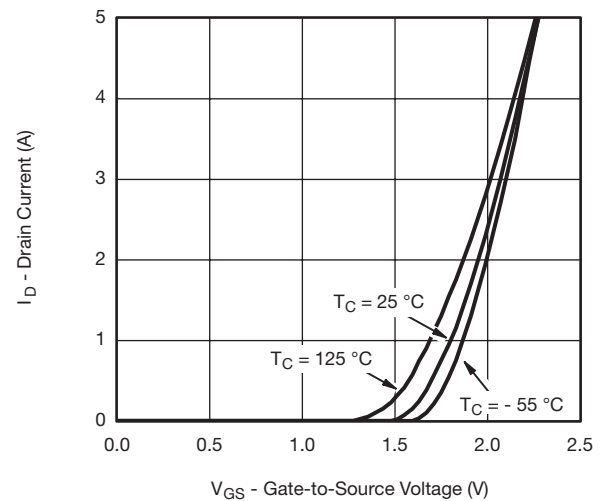
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

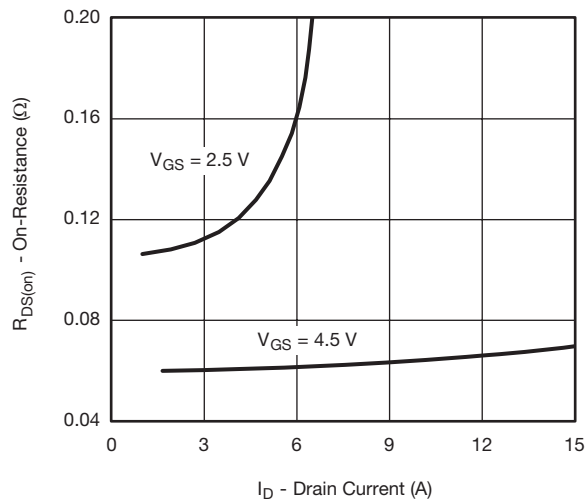
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



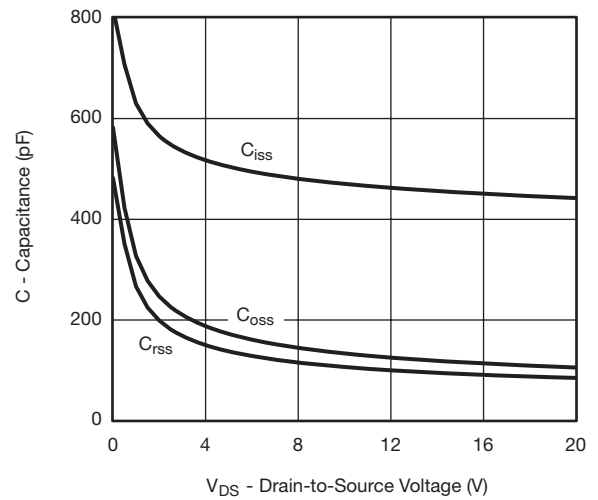
Output Characteristics



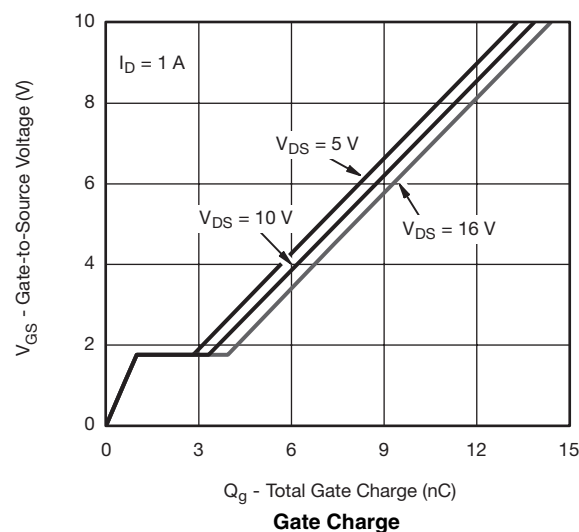
Transfer Characteristics



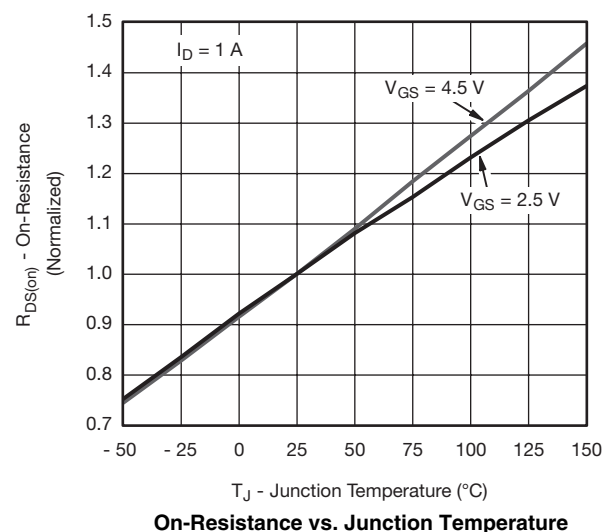
On-Resistance vs. Drain Current and Gate Voltage



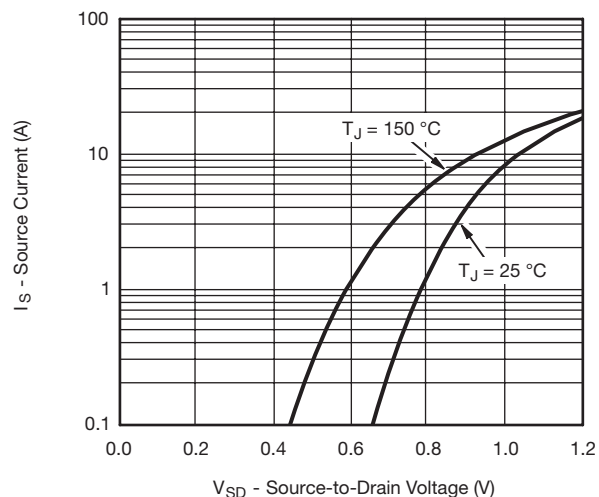
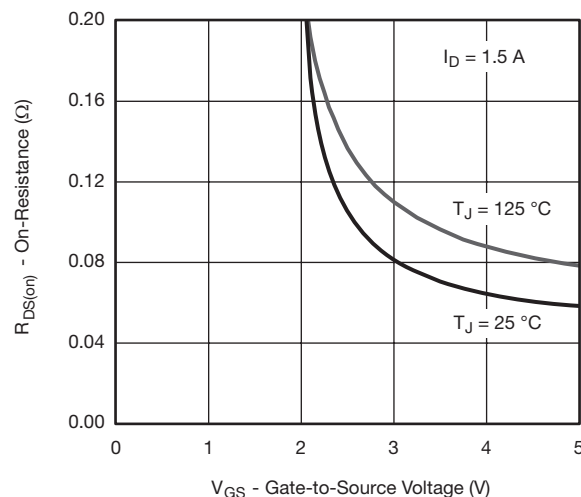
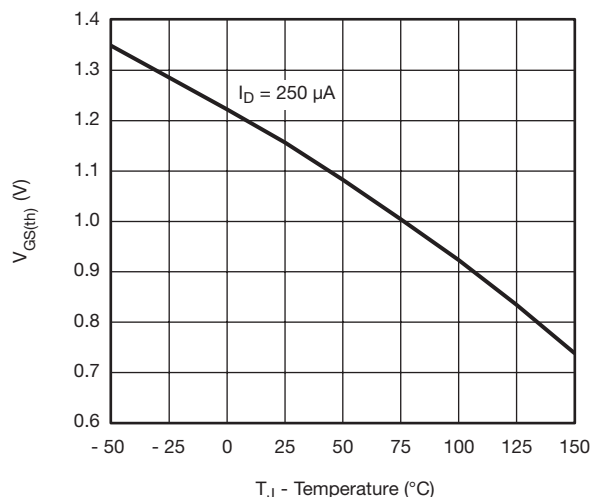
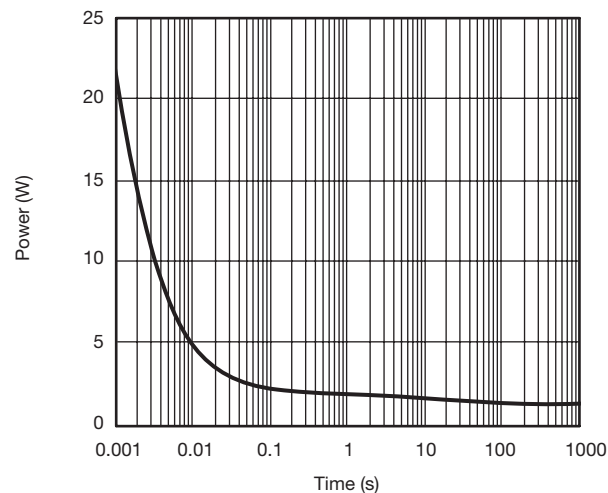
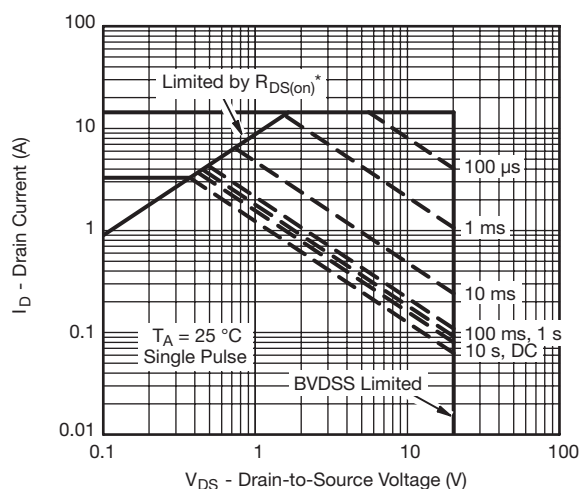
Capacitance



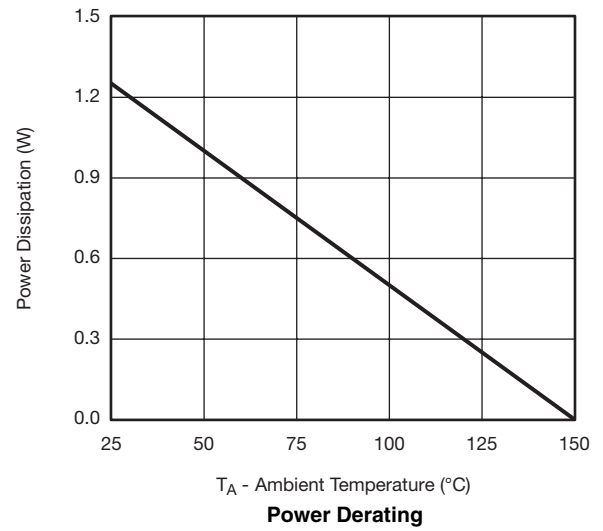
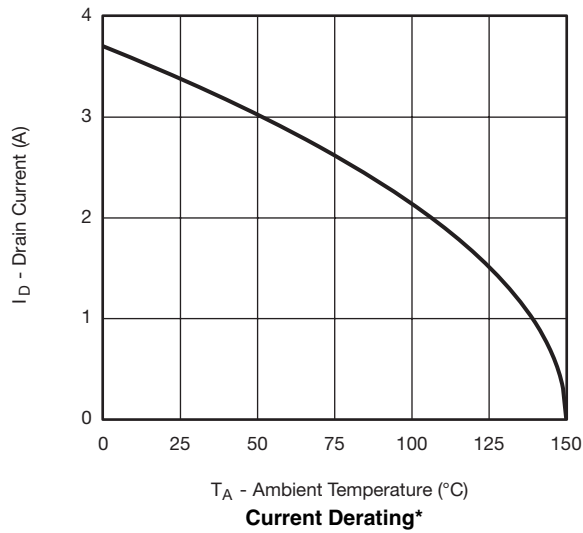
Gate Charge



On-Resistance vs. Junction Temperature

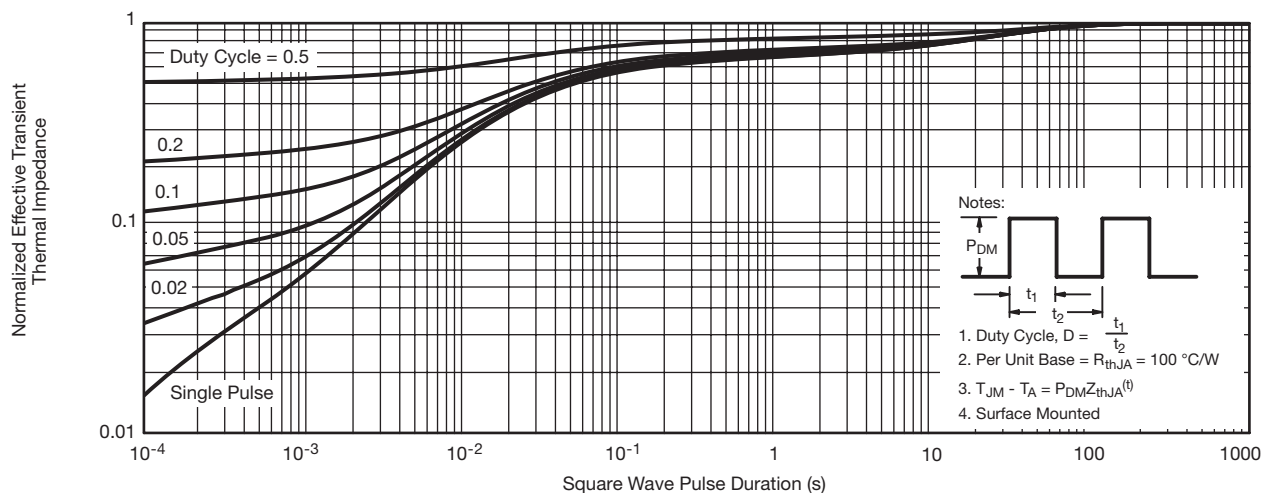
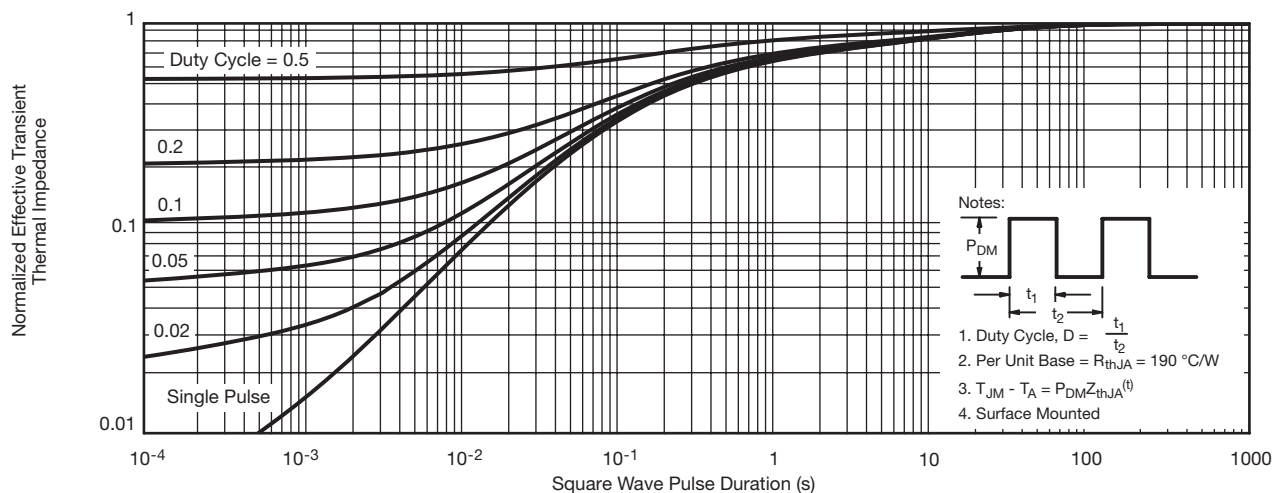
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power, Junction-to-Ambient*** $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified**Safe Operating Area, Junction-to-Ambient**

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



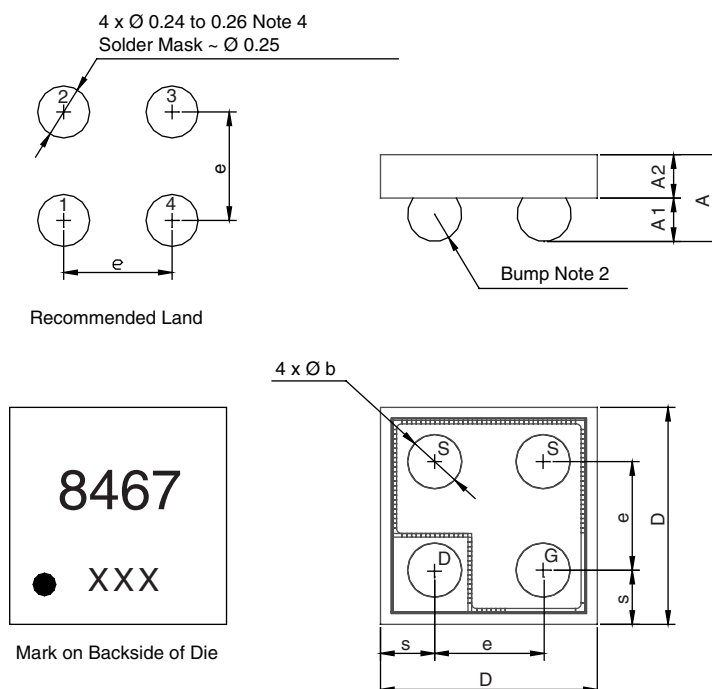
Note:
When mounted on 1" x 1" FR4 with full copper.

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Normalized Thermal Transient Impedance, Junction-to-Ambient (1" x 1" FR4 Board with Full Copper)

Normalized Thermal Transient Impedance, Junction-to-Ambient (1" x 1" FR4 Board with Minimum Copper)

PACKAGE OUTLINE

MICRO FOOT: 4-BUMP (2 x 2, 0.5 mm PITCH)



Notes (Unless otherwise specified):

1. All dimensions are in millimeters.
2. Four (4) solder bumps are lead (Pb)-free 95.5Sn/3.8Ag/0.7Cu with diameter Ø 0.30 mm to 0.32 mm.
3. Backside surface is coated with a Ti/Ni/Ag layer.
4. Non-solder mask defined copper landing pad.
5. • is location of pin 1.

Dim.	Millimeters ^a			Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.462	0.505	0.548	0.0181	0.0198	0.0215
A ₁	0.220	0.250	0.280	0.0086	0.0098	0.0110
A ₂	0.242	0.255	0.268	0.0095	0.0100	0.0105
b	0.300	0.310	0.320	0.0118	0.0122	0.0126
e	0.500			0.0197		
s	0.230	0.250	0.270	0.0090	0.0098	0.0106
D	0.920	0.960	1.000	0.0362	0.0378	0.0394

Notes:

- a. Use millimeters as the primary measurement.

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